

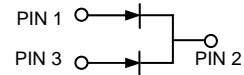
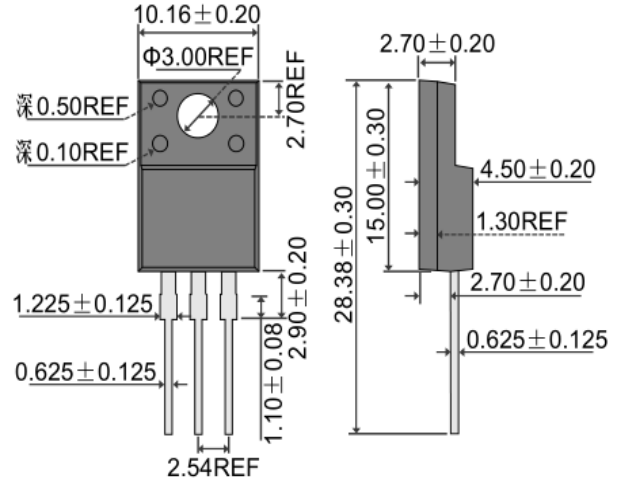
Features

- Power Schottky Barrier Chip
- Ultrafast 50nS and 100nS Recovery Time
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Surge Current Capability
- Epoxy Meets UL 94V-0 Classification
- Ideally Suited for Use in High Frequency SMPS, Inverters and As Free Wheeling Diodes

Mechanical Data

- Case: ITO-220, Full Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 1.9 grams (approx.)
- Mounting Position: Any
- Mounting Torque: 0.6 N.m Max.
- **Lead Free: For RoHS / Lead Free Version**

ITO-220AB



Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	UF 1000FCT	UF 1001FCT	UF 1002FCT	UF 1003FCT	UF 1004FCT	UF 1006FCT	UF 1008FCT	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	50	100	200	300	400	600	800	V
Working Peak Reverse Voltage	V _{RWM}								
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	210	280	420	560	V
Average Rectified Output Current @T _C = 100°C	I _O	10 5.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	125							A
Forward Voltage per diode @I _F = 5.0A	V _{FM}	1.0			1.3		1.7		V
Peak Reverse Current At Rated DC Blocking Voltage	I _{RM}	10 400							μA
Reverse Recovery Time (Note 1)	t _{rr}	50					100		nS
Typical Junction Capacitance (Note 2)	C _J	60					40		pF
Thermal Resistance Junction to Ambient per diode	R _{JA}	62							°C/W
Thermal Resistance Junction to Case per diode	R _{JC}	4.5							
RMS Isolation Voltage, t = 1 min	V _{ISO}	1500							V
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150							°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

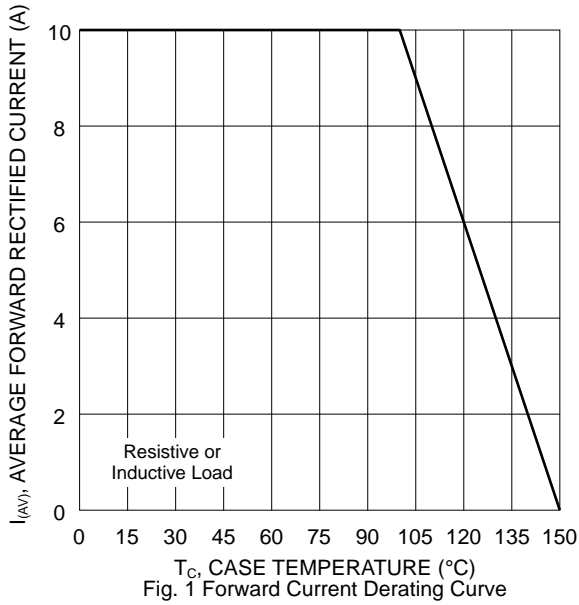


Fig. 1 Forward Current Derating Curve

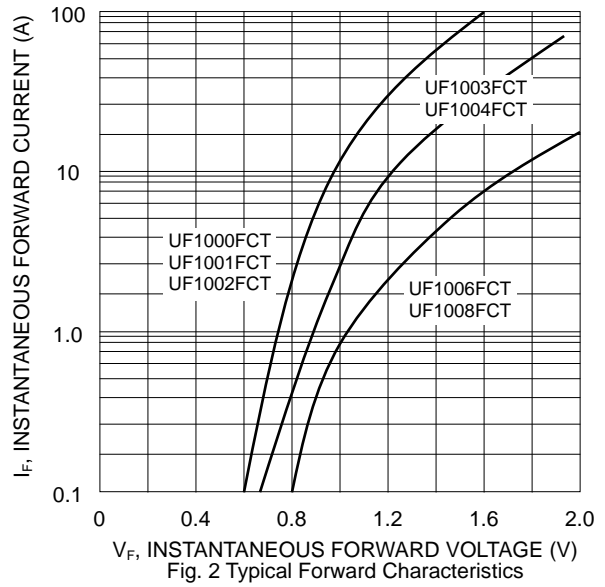


Fig. 2 Typical Forward Characteristics

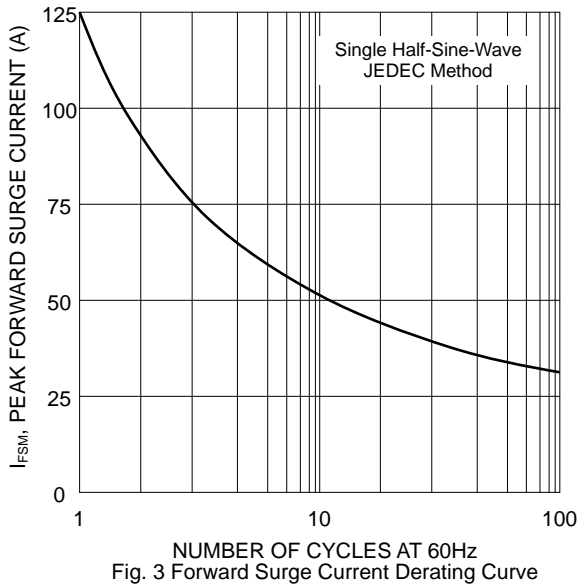


Fig. 3 Forward Surge Current Derating Curve

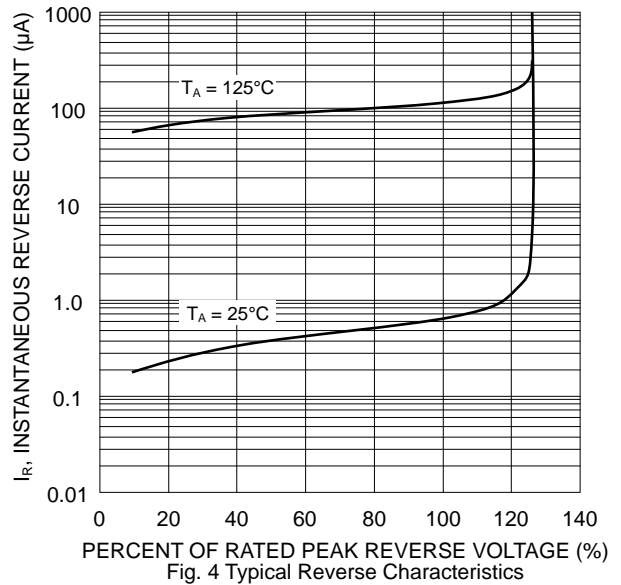


Fig. 4 Typical Reverse Characteristics

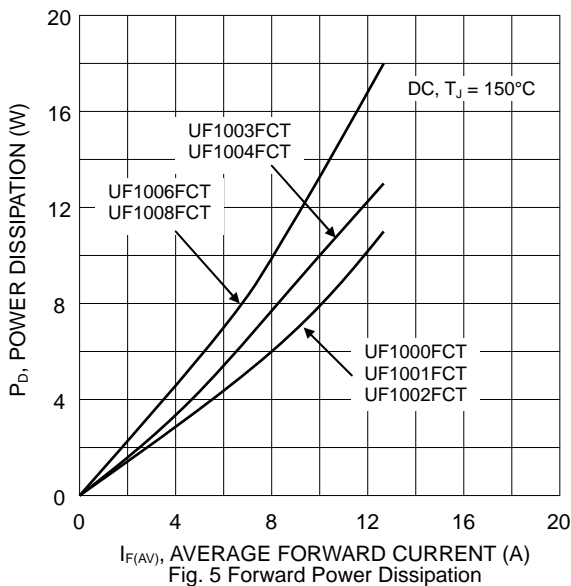


Fig. 5 Forward Power Dissipation

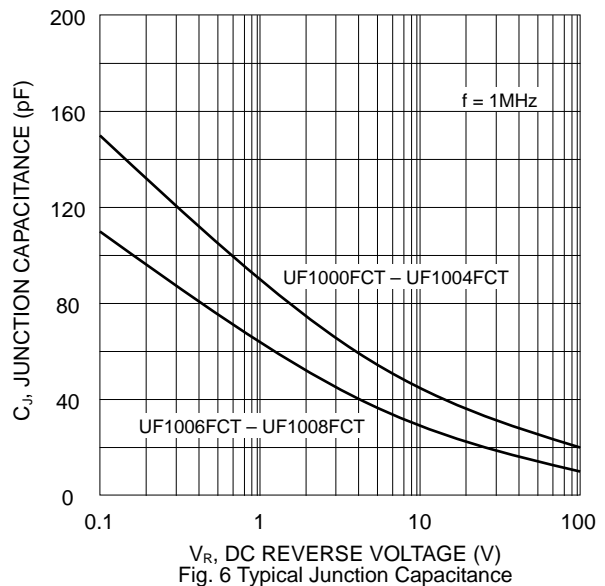
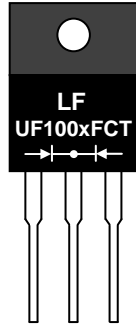


Fig. 6 Typical Junction Capacitance

MARKING INFORMATION



UF100xCT = Device Number
 x = 0, 1, 2, 3, 4, 6 or 8
 Polarity = As Marked on Body

PACKAGING INFORMATION

BULK

Tube Size L x W x H (mm)	Quantity (PCS)	Inner Box Size L x W x H (mm)	Quantity (PCS)	Carton Size L x W x H (mm)	Quantity (PCS)	Approx. Gross Weight (KG)
525 x 31 x 6	50	558 x 150 x 40	1,000	570 x 235 x 170	5,000	11.85

RECOMMENDED SCREW MOUNTING ARRANGEMENT

The full molded plastic package affords a major reduction of hardware as compared to a standard TO-220 package. However, precautions should be made in mounting procedure.

A conical washer should be used to apply proper force to the device. Screw should not be tightened with any type of air-forced torque or equipment that may cause crack on device package.

A layer of thermal grease or thermal pad in the interface will be considerably helpful for heat dissipation.

